



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBC3 Series SMT Female Header	SPEC.NO.: SPCB008D
REVISIONS	ECNT120076		PAGE: 1/5

1. SCOPE:

This specification contains the test requirement of subject pin headers when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD -202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
JIS - C - 5402	Methods for test of connectors for electronic equipment
UL 94	Test for flammability of plastic materials for parts in devices and
appliance	
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components , LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: CBC3 SERIES

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

(P.C. Board on which the Pin Header are installed), 1.6 mm (.063")

REVIEWED : Eisley APPROVED : Eisley VERIFIED : Michelle .



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBC3 Series SMT Female Header	SPEC.NO.: SPCB008D
REVISIONS	ECNT120076		PAGE: 2/5

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		Current: 0.5A Per Contact Voltage: 200VAC;300DC (r.m.s)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 10 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 500 V 1minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 100 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Push pin from insulator base at speed 25± 3 mm per minute	More than 0.5 Kgf
8.2	Single contact withdrawal force	Measure force to withdrawal using 0.3 mm square pin at speed 25± 3 mm per minute	More than 0.03 Kgf
8.3	Mating Force	Speed 25± 3 mm per minute	0.35kgf x (no. of Contacts) max.
8.4	Unmating Force	Speed 25± 3 mm per minute	0.05kgf x (no. of Contacts) min
8.5	Durability	Connector shall be subjected to 30 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBC3 Series SMT Female Header	SPEC.NO.: SPCB008D
REVISIONS	ECNT120076		PAGE: 3/5

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: $230 \pm 5^{\circ}\text{C}$ Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 90% of immersed area
9.2	Resistance to soldering heat	SMT Type Tin-Lead Process: Refer Reflow temperature profile(11.1) Soldering time: 10 second Max. Soldering pot: $230 \pm 5^{\circ}\text{C}$ SMT Type Lead-Free Process: Soldering time: 20 second Max. Soldering pot: $250\sim 260^{\circ}\text{C}$ Refer Reflow temperature profile(11.2)	No damage
9.3	Heat aging	$105 \pm 2^{\circ}\text{C}$, 96 hours	No damage
9.4	Humidity	$40 \pm 2^{\circ}\text{C}$, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of : (1)- $55^{+0}_{-3}^{\circ}\text{C}$, 30 min. (2)Room temp. 10-15 min. (3) $85^{+3}_{-0}^{\circ}\text{C}$, 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBC3 Series SMT Female Header	SPEC.NO.: SPCB008D
REVISIONS	ECNT120076		PAGE: 4/5

	ITEM	TEST CONDITION	REQUIREMENT
9.6	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

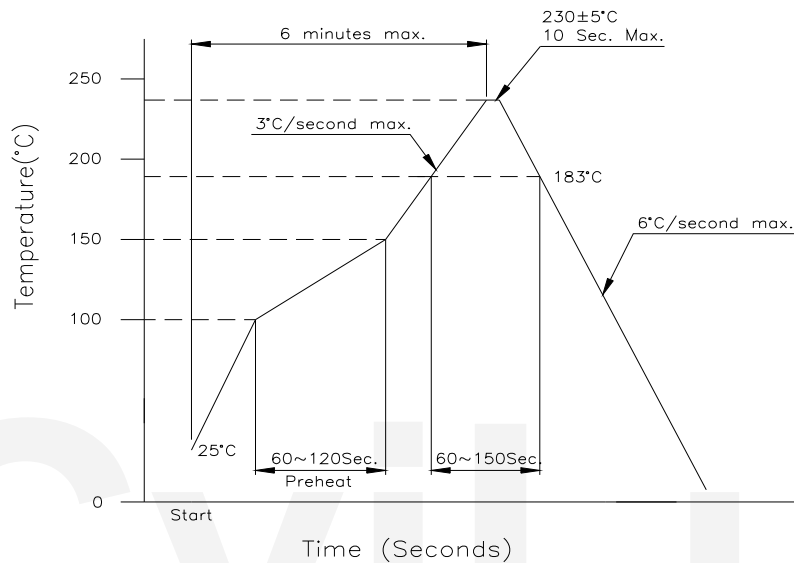
10. AMBIENT TEMPERATURE RANGE:

-40 to +85°C; + 215°C intermittent (Vapor Phase Solder Reflow) for SMT typ

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBC3 Series SMT Female Header	SPEC.NO.: SPCB008D
REVISIONS	ECNT120076		PAGE: 5/5

11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste



11.2 Using Lead-Free Solder Paste

